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Response to Office Action dated June 29, 2004

PATENT

**Amendments to the Claims**

This listing will replace all prior versions, and listings, of claims in the application:

Claim 1 (Previously Presented): A process for removing photoresist from semiconductor wafers comprising:

positioning at least one semiconductor wafer in a process tank; and

introducing a mixture of ozone and deionized water to the process tank via a sparger plate at an increased flow velocity across said wafer while said wafer is submerged in said deionized water and ozone.

Claim 2 (Cancelled).

Claim 3 (Previously Presented): The process according to claim 1 further comprising maintaining the temperature in the processing tank at ambient temperature.

Claim 4 (Original): The process according to claim 3 wherein the temperature is about 20-21 ° C.

Claim 5 (Original): The process according to claim 3 wherein the temperature is above 20-21 ° C.

Claim 6 (Original): The process according to claim 1 wherein the mixture of ozone and deionized water is recirculated and flows back into the processing tank.

Claim 7 (Original): The process according to claim 1 wherein the mixture of deionized water and ozone is recirculated and ozone added so as to keep the concentration of ozone in said mixture about constant.

Claim 8 (Original): The process according to claim 7 wherein said mixture of deionized water and ozone is agitated via the sparger plate.